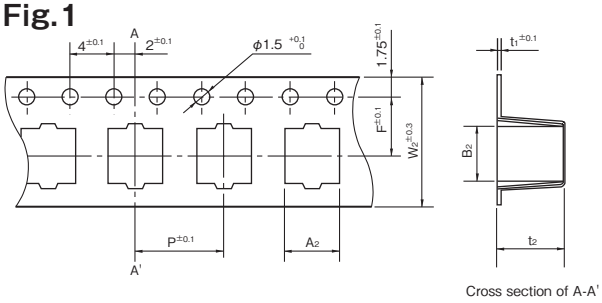
Chip type capacitors

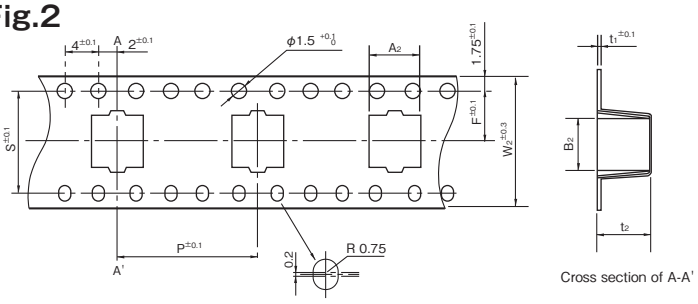
◆TAPING DIMENSIONS

Fig.1



Cross section of A-A'

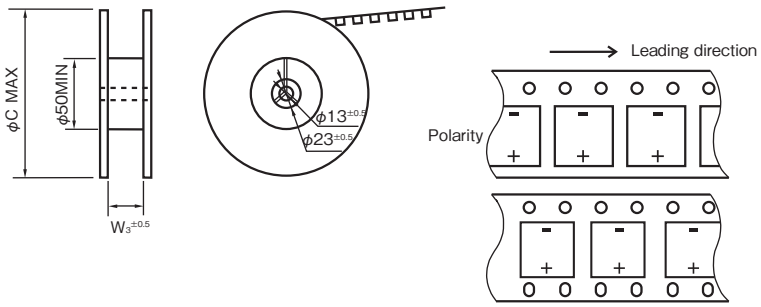
Fig.2



Cross section of A-A'

Size	W2 (mm)	A2 (mm)	B2 (mm)	P (mm)	t2 (mm)	F (mm)	t1 (mm)	S (mm)	Applicable
φ4×5.5	12.0	4.7	4.7	8	5.7	5.5	0.4	–	Fig.1
φ5×5.5	12.0	5.7	5.7	12	5.7	5.5	0.4	–	
φ6.3×5.5	16.0	7.0	7.0	12	5.7	7.5	0.4	–	
φ4×6.1	12.0	4.7	4.7	8	6.2	5.5	0.4	–	
φ5×6.1	12.0	5.7	5.7	12	6.2	5.5	0.4	–	
φ6.3×6.1	16.0	7.0	7.0	12	6.2	7.5	0.4	–	
φ6.3×8	16.0	7.0	7.0	12	8.2	7.5	0.4	–	
φ8×6.5	16.0	8.7	8.7	12	6.8	7.5	0.4	–	
φ8×10.5	24.0	8.7	8.7	16	11.0	11.5	0.4	–	
φ10×10.5	24.0	10.7	10.7	16	11.0	11.5	0.4	–	
φ12.5×13.5	32.0	13.4	13.4	24	14.4	14.2	0.5	28.4	Fig.2
φ12.5×16	32.0	13.4	13.4	24	16.3	14.2	0.5	28.4	
φ16×16.5	44.0	17.5	17.5	28	17.4	20.2	0.5	40.4	
φ16×21.5	44.0	17.5	17.5	28	22.4	20.2	0.5	40.4	
φ18×16.5	44.0	19.5	19.5	32	17.4	20.2	0.5	40.4	
φ18×21.5	44.0	19.5	19.5	32	22.4	20.2	0.5	40.4	

◆TAPING REEL AND PACKING QUANTITY



Size	W3 (mm)	φC (mm)	Quantity/reel	Standard Shipping Carton Quantity
φ4×5.5,6.1	14	382	2,000	10,000
φ5×5.5,6.1	14	382	1,000	5,000
φ6.3×5.5,6.1	18	382	1,000	5,000
φ6.3×8	18	382	900	4,500
φ8×6.5	18	382	1,000	5,000
φ8×10.5	26	382	500	2,000
φ10×10.5	26	382	500	2,000
φ12.5×13.5	34	332	200	600
φ12.5×16	34	332	150	450
φ16×16.5,φ18×16.5	46	332	125	250
φ16×21.5,φ18×21.5	46	332	75	150

Reuseable reels are available according to your request.
Please consult in regard to establishing supply and withdrawal system.

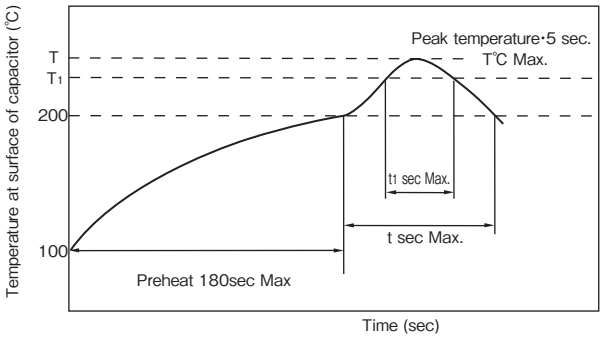
◆LEAD FREE TYPE REFLOW SOLDERING CONDITION

●Size φ4～φ10

1) Temperature at surface of capacitor shall not exceed T℃.

2)Period that temperature at surface of capacitor becomes more than 200℃ and T_1℃ shall not exceed t and t_1 seconds, respectively.

3)Preheat shall be made at 100℃～200℃ and for maximum 180 seconds.



Series	Size	T(℃) ①	T_1(℃)	t(sec) ②	t_1(sec) ③	Reflow cycle
SGV TZV	φ4～φ6.3	250	230	90	40	1
TXV TLV	φ8	240	230	90	30	1
THV TKV	φ10	235	230	60	30	1
SJV SLV	φ4～φ6.3	240	220	60	40	1
JGV	φ4～φ6.3	260	217	—	60	2
JZV	φ8,φ10	250	217	—	60	2

①Peak temperature

②〈MAX〉 Time more than 200℃

③〈MAX〉 Time more than T_1

※Please contact us if the condition is over the maximum.

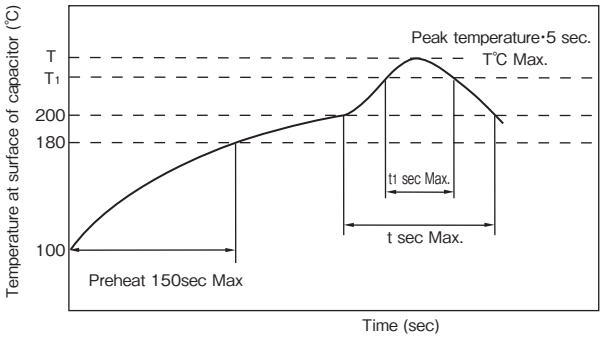
◆LEAD FREE TYPE REFLOW SOLDERING CONDITION

●Size φ12.5～φ18

1)Temperature at surface of capacitor shall not exceed T℃.

2)Period that temperature at surface of capacitor becomes more than 200℃ and T_1℃ shall not exceed t and t_1 seconds, respectively.

3)Preheat shall be made at 100℃～180℃ and for maximum 150 seconds.



Series	Size	T(℃) ①	T_1(℃)	t(sec) ②	t_1(sec) ③	Reflow cycle
SGV TLV	φ12.5 ～φ18	240	230	60	30	1

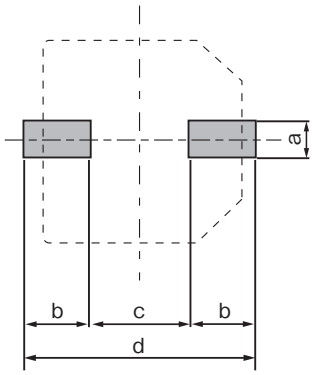
①Peak temperature

②〈MAX〉 Time more than 200℃

③〈MAX〉 Time more than T_1

※Please contact us if the condition is over the maximum.

◆RECOMMENDED LAND SIZE



(mm)

Size	a	b	c	d
φ4	1.6	2.6	1.0	6.2
φ5	1.6	3.0	1.4	7.4
φ6.3	1.6	3.5	2.1	9.1
φ8×6.5	1.6	4.5	2.1	11.1
φ8×10.5	2.2	4.1	3.0	11.2
φ10×10.5	2.2	4.3	4.5	13.1
φ12.5	2.5	6.0	5.0	17
φ16	3	6.5	8.0	21
φ18	3	7.5	8.0	23

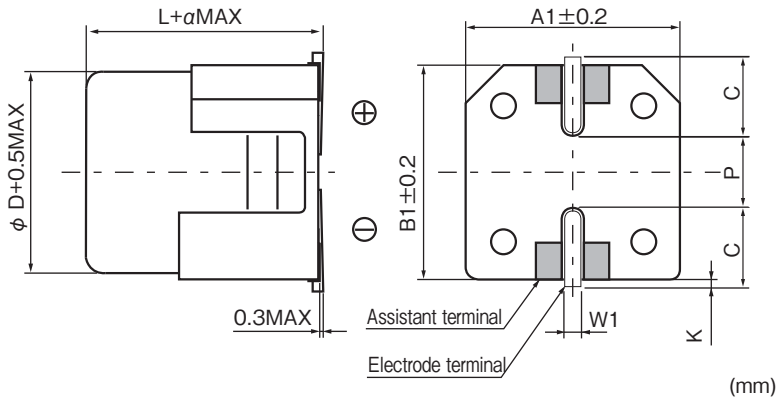
◆Vibration proof packages with the supporting terminal

●For chip Aluminum electrolytic capacitors more than case size ϕ 8, vibration proof packages supports.

◆PART NUMBER

□□□	□□□	□□□□□	□	□□□	VB	D×L
Rated Voltage	Series	Rated Capacitance	Capacitance Tolerance	Option	Vibration proof package No.	Case Size

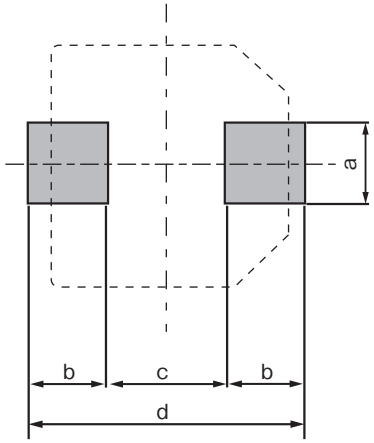
◆DIMENSIONS



(mm)

Size(φD×L)	A1	B1	C	W1	P	K	α
8×10.5	8.3	8.3	3.1	0.9±0.2	3.1	0.5±0.4	0.5
10×10.5	10.3	10.3	3.4	0.9±0.2	4.5	0.5±0.4	0.5
12.5×13.5	13	13	4.9	1.1±0.3	4.5	0.7±0.4	1
12.5×16	13	13	4.9	1.1±0.3	4.5	0.7±0.4	1
16×16.5	17	17	6	1.1±0.3	6.8	0.7±0.4	1
16×21.5	17	17	6	1.1±0.3	6.8	0.7±0.4	1
18×16.5	19	19	7	1.1±0.3	6.8	0.7±0.4	1
18×21.5	19	19	7	1.1±0.3	6.8	0.7±0.4	1

◆RECOMMENDED LAND SIZE



(mm)

Size(φD×L)	a	b	c	d
8×10.5	4.2	4.5	2.5	11.5
10×10.5	4.2	4.8	3.9	13.5
12.5	6.4	6.2	3.9	16.3
16	7	7.8	4.7	20.3
18	7	8.8	4.7	22.3